

PATENT
Customer No. 22,852
Attorney Docket No. 4329.2197-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Divisional Application of:

Masaki ADACHI et al.

Serial No.: Not Yet Assigned

Filed: June 1, 2001

For: COMPOSITION FOR SEALING A
SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE
SAME

) Parent Application:
) Serial No. 09/451,755

) Filed: December 1, 1999

) Group Art Unit: 2811

) Examiner: N. Parekh

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

PRELIMINARY AMENDMENT

Prior to the examination of the above application, please amend this application
as follows:

IN THE CLAIMS:

Please cancel claim 1 without prejudice to, or disclaimer of, the subject matter
thereof and add new claims 21-32 as follows.

para 9 poly phenylene sulfide

--21. (New) A thermoplastic material suitable for sealing a part of a conducting
material and a semiconductor element electrically coupled with the conducting material,